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(54) Title: COMPACT DYNAMIC LEVELING LIFT MECHANISM

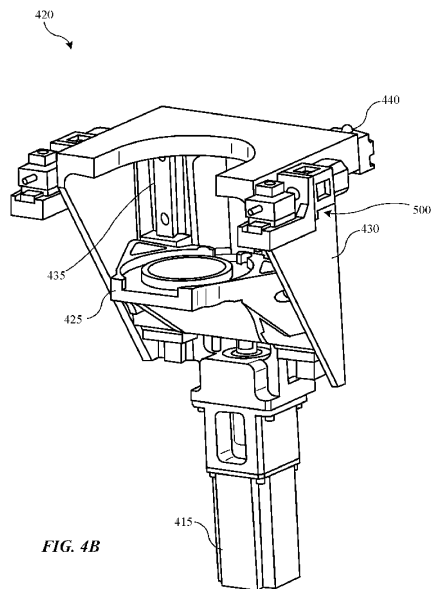


FIG. 4B

(57) Abstract: Exemplary semiconductor processing chambers may include a chamber body. The chambers may include a bottom plate coupled with a bottom surface of the chamber body. The chambers may include a substrate support assembly disposed within the chamber body. The substrate support assembly may include a support plate and a support stem coupled with the support plate. The chambers may include a mounting bracket that couples the support stem with a lower surface of the bottom plate. The chambers may include a plurality of tilt actuators. Each of the tilt actuators may couple the mounting bracket with the lower surface of the bottom plate. Each of the tilt actuators may be operable to adjust a vertical distance between the lower surface of the bottom plate and the mounting bracket at a mounting site of the respective tilt actuator to adjust a planarity of the support plate relative to the bottom plate.

WO 2025/080668 A1